

• General Description

The CH30N06A combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

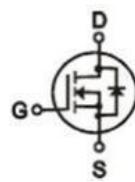
• Features

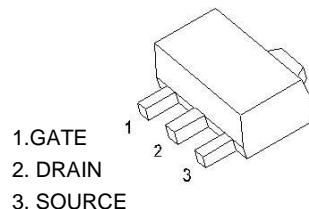
- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

• Product Summary


 $V_{DS} = 60V$
 $R_{DS(ON)} = 23m\Omega$
 $I_D = 30A$

SOT-89-3L


• Ordering Information:

Part NO.	CH30N06A
Marking	CH30N06A
Packing Information	REEL TAPE
Basic ordering unit (pcs)	1000

• Absolute Maximum Ratings ($T_c = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	20	V
Continuous Drain Current	$I_D@T_c=25^\circ C$	30	A
	$I_D@T_c=75^\circ C$	25	A
	$I_D@T_c=100^\circ C$	20	A
Pulsed Drain Current	I_{DM}	120	A
Total Power Dissipation($T_c=25^\circ C$)	$P_D@T_c=25^\circ C$	45	W
Total Power Dissipation($T_A=100^\circ C$)	$P_D@T_c=100^\circ C$	30	W
Operating Junction Temperature	T_J	-55 to 175	°C
Storage Temperature	T_{STG}	-55 to 175	°C
Single Pulse Avalanche Energy@ $L=0.1mH$	E_{AS}	120	mJ
Avalanche Current@ $L=0.1mH$	I_{AS}	50	A

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	2.7		°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	100	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	125	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA	60			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250μA	1	1.6	2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} = ±12V , V _{DS} = 0V			±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 15A		23	30	mΩ
		V _{GS} = 4.5V, I _D = 10A		29	40	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 5V, I _D = 10A		11		s
Source-drain voltage	V _{SD}	I _S = 20A			1.20	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz	-	1073	-	pF
Output capacitance	C _{oss}		-	65.4	-	
Reverse transfer capacitance	C _{rss}		-	56.8	-	

•Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q _g	V _{DS} = 30V I _D = 15A V _{GS} = 10V	-	25	-	nC
Gate - Source charge	Q _{gs}		-	4.5	-	
Gate - Drain charge	Q _{gd}		-	6.5	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

Typical Electrical and Thermal Characteristics (Curves)

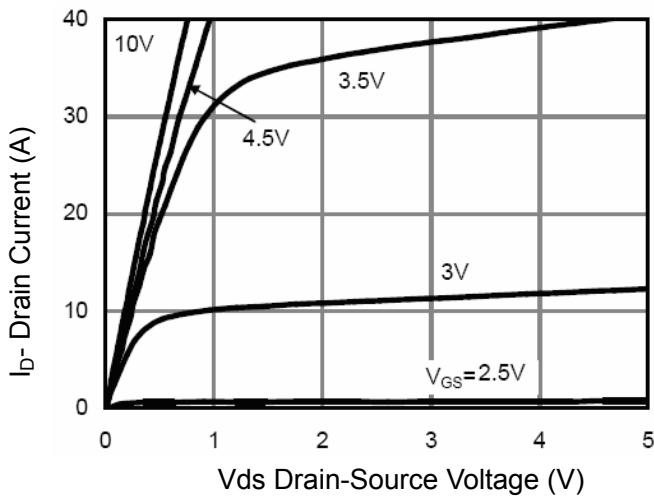


Figure 1 Output Characteristics

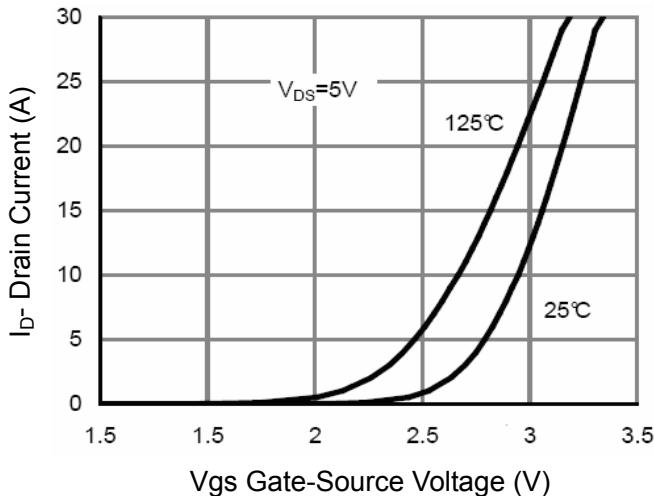


Figure 2 Transfer Characteristics

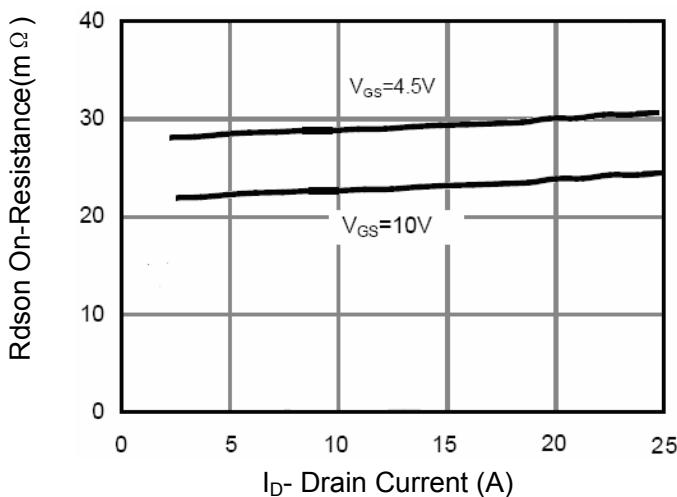


Figure 3 Rdson- Drain Current

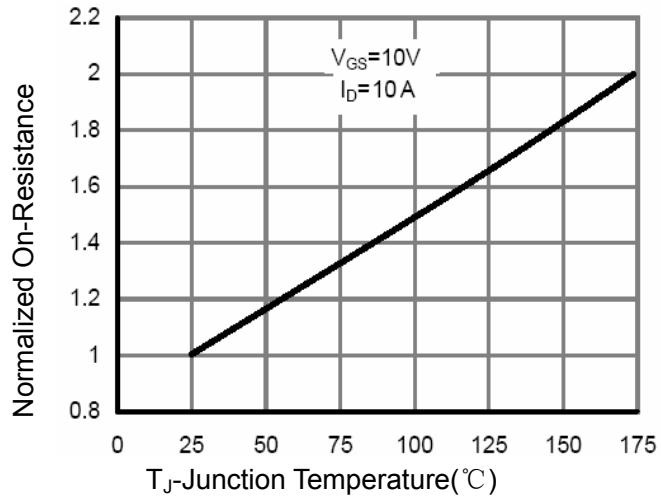


Figure 4 Rdson-Junction Temperature

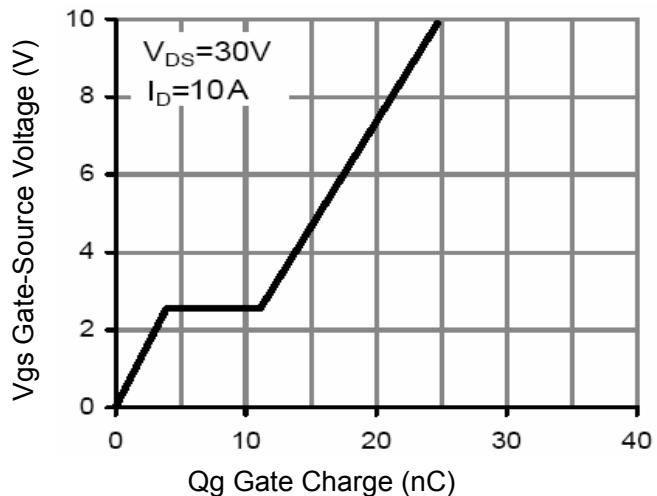


Figure 5 Gate Charge

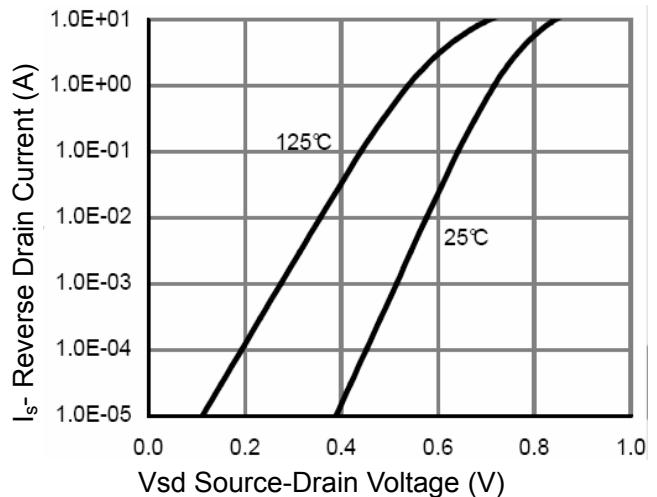


Figure 6 Source- Drain Diode Forward

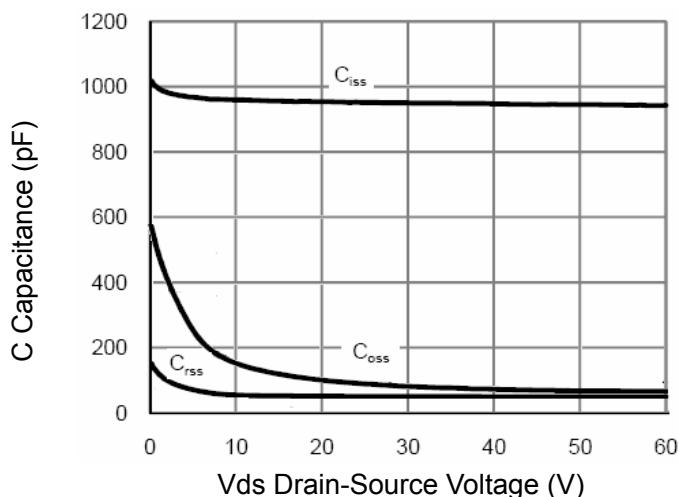


Figure 7 Capacitance vs Vds

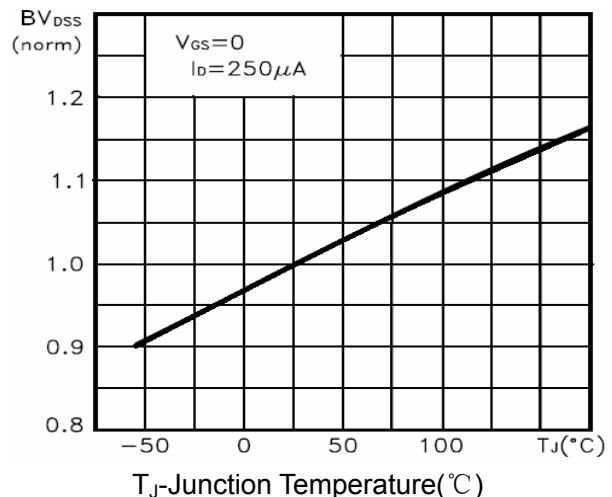


Figure 9 BV_{DSS} vs Junction Temperature

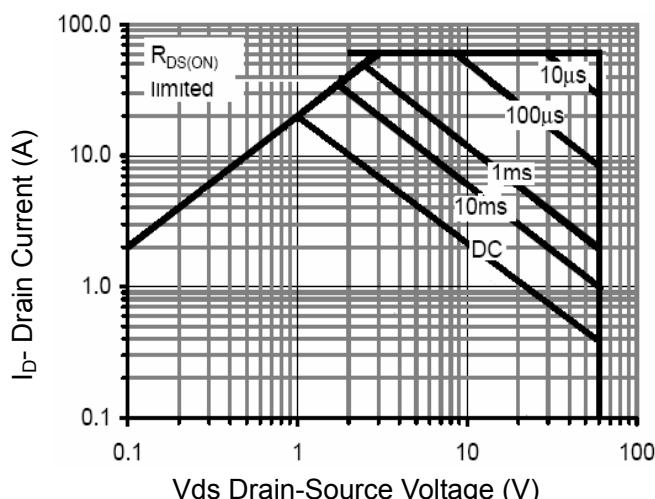


Figure 8 Safe Operation Area

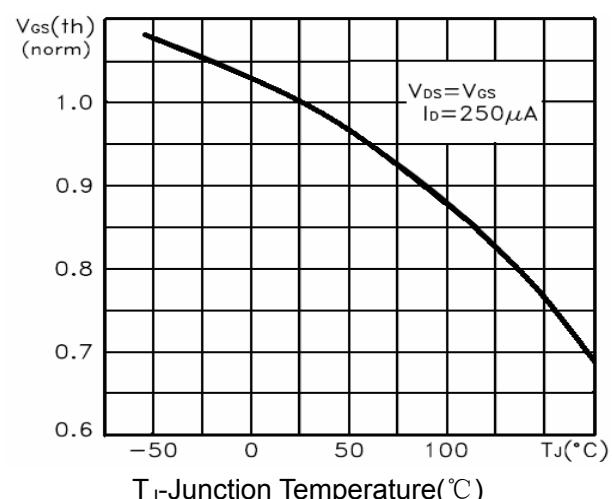


Figure 10 $V_{GS(th)}$ vs Junction Temperature

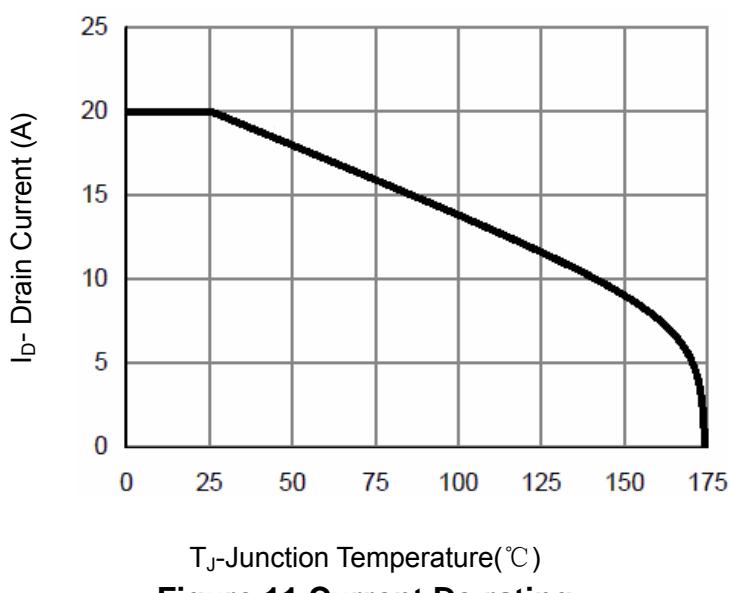
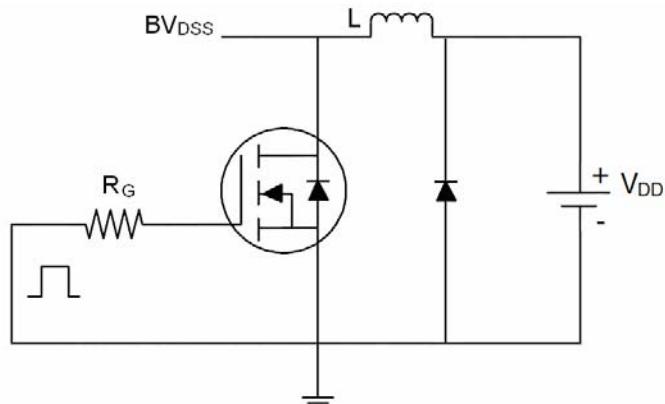


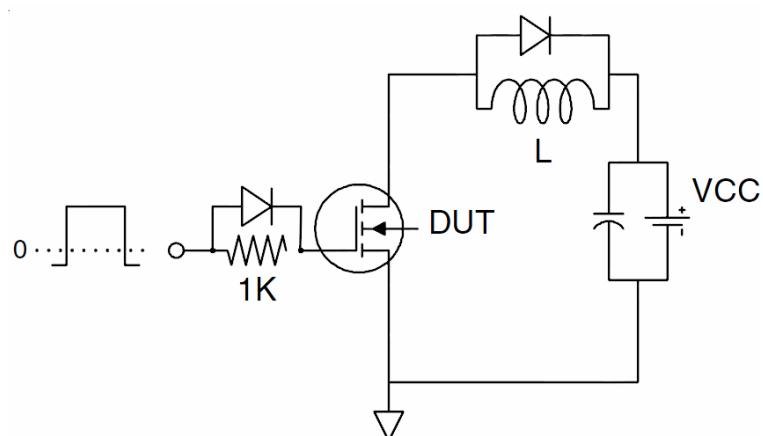
Figure 11 Current De-rating

Test Circuit

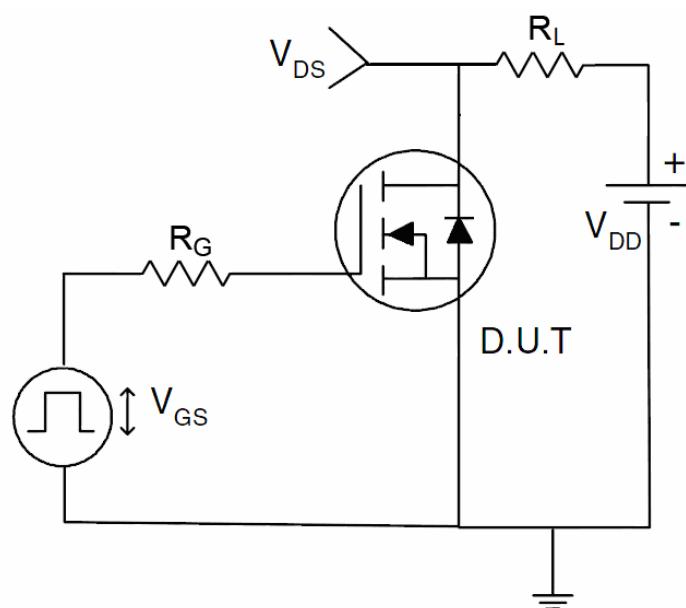
1) E_{AS} test Circuit

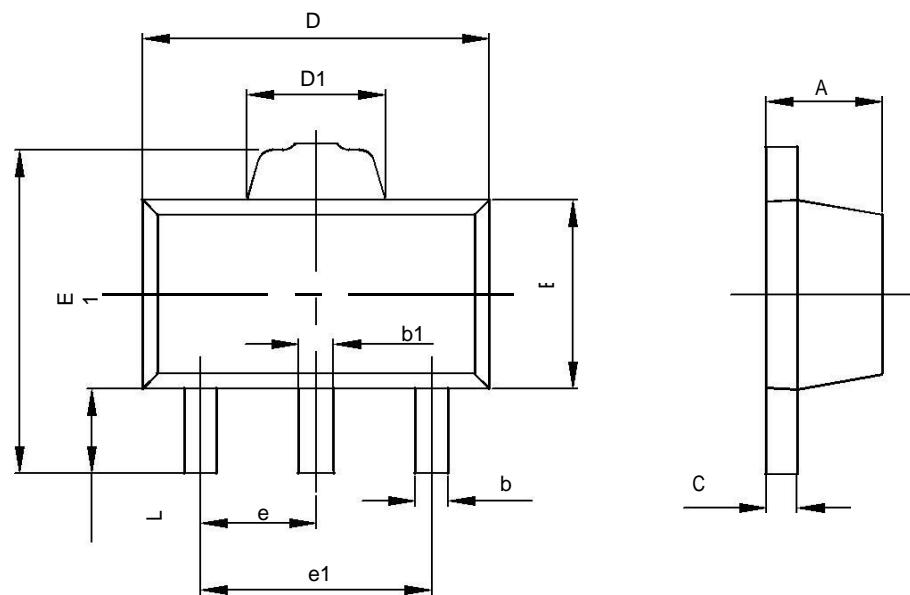


2) Gate charge test Circuit



3) Switch Time Test Circuit



SOT-89-3L PACKAGE OUTLINE DIMENSIONS


Symbol	Dimensions In Millimeters			Dimensions In Inches	
	Min		Max	Min	Max
A	1.400		1.600	0.055	0.063
b	0.320		0.520	0.013	0.020
b1	0.360		0.560	0.014	0.022
c	0.350		0.440	0.014	0.017
D	4.400		4.600	0.173	0.181
D1	1.400		1.800	0.055	0.071
E	2.300		2.600	0.091	0.102
E1	3.940		4.250	0.155	0.167
e	1.500TYP			0.060TYP	
e1	2.900		3.100	0.114	0.122
L	0.900		1.100	0.035	0.043